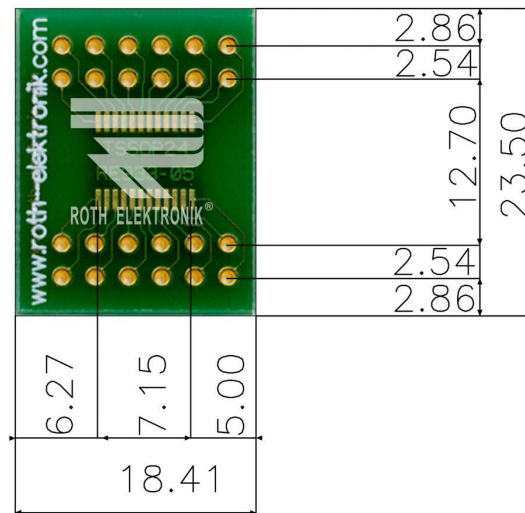


#### RE933-05

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSSOP 24
- Pitch: 0.65 mm (173 mil)
- Hole diameter 1.00 mm
- Size 18.41 x 23.50 mm

Module-No. Pitch mil Pin Size (mm)

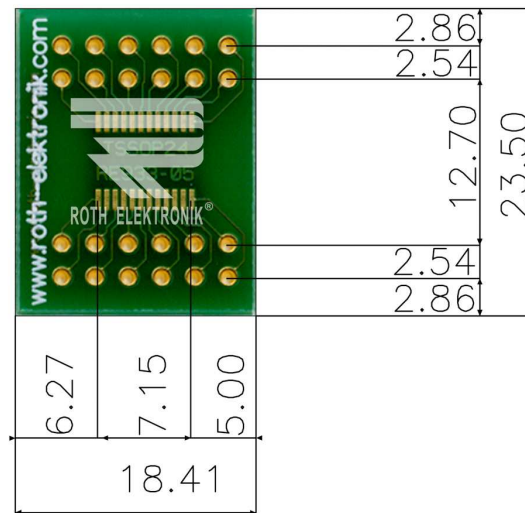
RE933-05 0.650 mm 22.5 24 4.400 (173 mil)



#### RE933-05

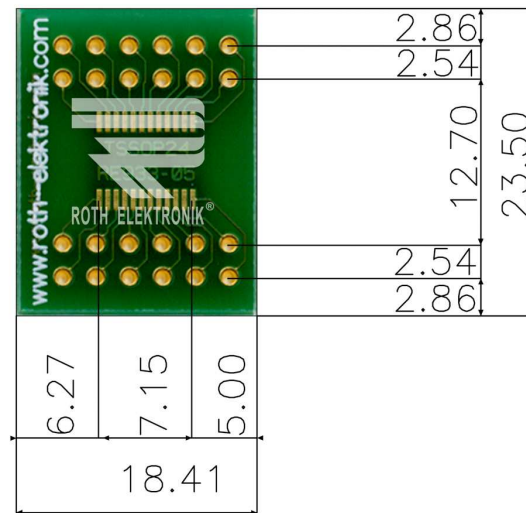
- Epoxydglashartgewebe FR4 1,50 mm
  - Zweiseitig 35 µm Cu
  - Durchkontaktiert (PTH)
  - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
  - Adaptionsplatine für TSSOP 24
  - Pitch: 0,65 mm (173 mil)
  - Lochdurchmesser 1,00 mm
  - Größe 18,41 x 23,50 mm
- Modul-Nr. Pitch mil Pin Größe (mm)

RE933-05 0,650 mm 22,5 24 4,400 (173 mil)



#### RE933-05

- Fibre de verre époxyde FR4 1,50 mm
  - Double face 35 µm Cu
  - Métallisation des trous (PTH)
  - Surface avec Ni/Au chimique et un laque d'arrêt de soudure
  - Platine d'adaptation pour TSSOP 24
  - Pitch: 0,65 mm (173 mil)
  - Perforation 1,00 mm Ø
  - Dimensions 18,41 x 23,50 mm
- Module-No. Pitch mil Pin Dimensions (mm)  
RE933-05 0.650 mm 22,5 24 4,400 (173 mil)



#### RE933-05

- Fibra de vidrio epoxídica FR4 1,50 mm
  - Por dos lados 35 µm de Cu
  - Agujeros con contactos metalizados (PTH)
  - Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
  - Adaptador para TSSOP 24
  - Pitch: 0,65 mm (173 mil)
  - Diámetro de agujeros 1,00 mm
  - Tamaño 18,41 x 23,50 mm
- Módulo-No. Pitch mil Pin Tamaño (mm)

RE933-05 0.650 mm 22.5 24 4.400 (173 mil)